

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	18	@ad<="20040318" and 'IC' with 'silicon' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:26
L3	4	@ad<="20040318" and 'IC chip' with 'silicon' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:23
L4	423	@ad<="20040318" and 'IC' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:27
L5	130	@ad<="20040318" and 'semiconductor chip' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:27
S1	2	"20040173891"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:13
S2	3	("6148900").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/21 12:14
S3	6	(("5859407") or ("6080936") or ("6115913")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/21 12:18
S4	3	@ad<="20040318" and 'interposer' with 'alumina' and 'IC' with 'silicon'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:22
S5	11	@ad<="20040318" and 'interposer' with 'alumina' and 'IC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:25
S6	14	@ad<="20040318" and 'interposer' same 'alumina' and 'IC chip'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:50

S7	240	@ad<="20040318" and 'board' same 'alumina' and 'IC chip'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:44
S8	123	@ad<="20040318" and 'board' with 'alumina' and 'IC chip'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:45
S9	2	@ad<="20040318" and 'board' with 'alumina' and 'interposer' and 'IC chip'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:45
S10	67	@ad<="20040318" and 'interposer' same 'alumina'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:52
S11	1	"20020041489".PN.	US-PGPUB	OR	ON	2005/07/21 12:52
S12	1	"6479760".PN.	USPAT; USOCR	OR	ON	2005/07/21 12:52
S14	7568	@ad<="20040318" and (174/260).ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. or (257/698).ccls. or (257/738).ccls. or (257/778).ccls. and 'alumina'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:03
S17	9082	@ad<="20040318" and (174/260).ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. or (257/698).ccls. or (257/738).ccls. or (257/778).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:59
S18	7568	@ad<="20040318" and (174/260).ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. or (257/698).ccls. or (257/738).ccls. or (257/778).ccls. and 'alumina'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:56
S19	7408	@ad<="20040318" and (174/260).ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. or (257/698).ccls. or (257/738).ccls. or (257/778).ccls. and 'alumina' near 'interposer' and 'IC chip' near 'silicon'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:00
S20	3	@ad<="20040318" and 'alumina' with 'interposer' and 'IC chip' with 'silicon'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:57
S22	1	"6085260".PN.	USPAT; USOCR	OR	ON	2005/07/21 13:02

S23	1	@ad<="20040318" and 'interposer' and 'IC chip' with 'silicon' same 'thermal expansion coefficient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:21
S24	150	@ad<="20040318" and 'IC' same 'silicon' same 'thermal expansion coefficient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:21
S25	76	@ad<="20040318" and 'IC' with 'silicon' with 'thermal expansion coefficient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:25
S26	162	@ad<="20040318" and 'thermal expansion coefficient' with 'silicon' with 'ppm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:29
S27	18	@ad<="20040318" and 'thermal expansion coefficient' with 'silicon' with 'ppm' and 'interposer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:40
S28	10	@ad<="20040318" and 'silicon' with 'ppm' and 'interposer' same 'inorganic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:40
S29	1562	@ad<="20040318" and (257/700).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:04
S30	1318	@ad<="20040318" and (29/852).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:04
S31	1229	@ad<="20040318" and (257/734).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:05
S32	4	(("6388198") or ("6222276")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/21 14:31
S33	14	@ad<="20040318" and 'interposer' with 'silicon nitride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 15:36

S34	2	("6507497").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/21 15:31
S35	28	@ad<="20040318" and 'interposer' same 'silicon nitride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:10
S37	601	@ad<="20040318" and 'board' with 'silicon' with 'silicon nitride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:11
S38	0	@ad<="20040318" and 'board' with 'silicon' with 'silicon nitride' same 'interposer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:12
S39	7	@ad<="20040318" and 'board' same 'silicon' same 'silicon nitride' same 'interposer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:12